

Overview

HP ProBook x360 435 G7 Notebook PC



Left

- 1. Internal Microphones
- 2. Webcam LED
- 3. Webcam and IR Camera (Optional)
- 4. HP Privacy Camera
- 5. IR Camera LED (Optional)
- 6. Clickpad
- 7. World-facing Camera (Optional)
- 8. World-facing Camera LED (Optional)
- 9. Vents
- 10. USB 3.1 Gen 1 Charging Port
- 11. Nano Security Lock Slot (Lock Sold Separately)

Overview



Right

- 1. Power Button
- 2. Power Connector
- 3. USB Type-C™ 3.1 Gen 1 Port
- 4. USB 3.1 Gen 1 Port
- 5. HDMI Port (Cable not included)
- 6. Audio Combo Jack
- 7. MicroSD Card Slot
- 8. Touch Fingerprint Sensor (Optional)

Overview

AT A GLANCE

- Preinstalled with Windows 10 versions or FreeDOS
- A stylish and professional convertible adapts with versatile use modes from traditional laptop to tablet, stand and tent that enables to create, present and collaborate
- Sleek and durable anodized aluminum top cover and keyboard deck
- Choice of AMD Ryzen™ 4000 series mobile processors
- Integrated AMD Radeon™ Graphics
- Display include your choice of 33.8 cm (13.3") diagonal IPS Wide Viewing Angle, FHD, touch screen with Corning® Gorilla® Glass 5
- Commercial-grade security features including HP Sure Start¹, HP Sure Sense², HP Client Security³, HP Sure Click⁴, HP Privacy Camera⁵ and optional HP Sure View⁶
- Captures the world around with an optional world facing- camera in the keyboard⁷
- Supports wireless LAN options for connectivity on the go including gigabit-speed Wi-Fi 6⁷
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles⁸
- Passed MIL-STD 810H tests⁹
- Battery life up to 17 hours and 15 minutes

1. HP Sure Start for AMD is available on select HP PCs with AMD processors. See product specifications for availability.

2. HP Sure Sense requires Windows 10. See product specifications for availability.

3. HP Client Security Manager requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.

4. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode. Check <http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW> for all compatible platforms as they become available.

5. HP Privacy Camera only available PCs equipped with HD or IR camera and must be installed at the factory

6. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape. Touch-enabled display and Sure View privacy panel will lower actual brightness.

7. Sold separately or as an optional feature.

8. HP notebooks up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

9. MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Technical Specifications

PRODUCT NAME

HP ProBook x360 435 G7 Notebook PC

OPERATING SYSTEM

Preinstalled

Windows® 10 Pro 64¹
 Windows® 10 Pro 64 (National Academic License)²
 Windows® 10 Home 64¹
 Windows® 10 Home Single Language 64¹
 Windows® 10 Enterprise 64 (Web Support)¹
 FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see <https://aka.ms/ProEducation> for Windows 10 Pro Education feature information.

Note: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on <http://www.support.hp.com>. A full list of HP products and the Windows 10 versions tested is available on the HP support website. <https://support.hp.com/us-en/document/c05195282>

PROCESSORS

AMD Ryzen™ 7 4700U APU with Radeon™ Graphics (2.0 GHz base clock, up to 4.1 GHz max boost clock, 8 MB L3 cache, 8 cores)^{3,4,5,6}

AMD Ryzen™ 7 PRO 4750U APU with Radeon™ Graphics (1.7 GHz base clock, up to 4.1 GHz max boost clock, 8 MB L3 cache, 8 cores)^{3,4,5,6}

AMD Ryzen™ 5 4500U APU with Radeon™ Graphics (2.3 GHz base clock, up to 4.0 GHz max boost clock, 8 MB L3 cache, 6 cores)^{3,4,5,6}

AMD Ryzen™ 5 PRO 4650U APU with Radeon™ Graphics (2.1 GHz base clock, up to 4.0 GHz max boost clock, 8 MB L3 cache, 6 cores)^{3,4,5,6}

AMD Ryzen™ 3 4300U APU with Radeon™ Graphics (2.7 GHz base clock, up to 3.7 GHz max boost clock, 4 MB L3 cache, 4 cores)^{3,4,5,6}

Processor Family

AMD Ryzen™ 4000 Series Mobile Processors⁶

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

5. Max Boost clock frequency performance varies depending on hardware, software and overall system configuration.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>

Technical Specifications

CHIPSET

Chipset is integrated with processor.

GRAPHICS

Integrated

AMD Radeon™ Graphics⁷

Supports

Support HD decode, DX12, HDMI1.4b, via HDMI up to 4K 30Hz

[7. HD content required to view HD images.](#)

DISPLAY

Touch

33.8 cm (13.3") diagonal FHD UWVA eDP BrightView WLED-backlit touch screen with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC with HD camera (1920 x 1080)^{7,8,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP BrightView WLED-backlit touch screen with Corning® Gorilla® Glass 5, 250 nits, 45% NTSC with HD + IR camera (1920 x 1080)^{7,8,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP + PSR BrightView WLED-backlit touch screen with Corning® Gorilla® Glass 5, Low Power, 400 nits, 72% NTSC with HD camera (1920 x 1080)^{7,8,9,10}

33.8 cm (13.3") diagonal FHD UWVA eDP + PSR BrightView WLED-backlit touch screen with Corning® Gorilla® Glass 5, Low Power, 400 nits, 72% NTSC with HD + IR camera (1920 x 1080)^{7,8,9,10}

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD UWVA eDP + PSR BrightView WLED-backlit touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with HD camera (1920 x 1080)^{7,8,9,10,11}

HP Sure View Integrated Privacy Screen 33.8 cm (13.3") diagonal FHD UWVA eDP + PSR BrightView WLED-backlit touch screen with Corning® Gorilla® Glass 5, 1000 nits, 72% NTSC with HD + IR camera (1920 x 1080)^{7,8,9,10,11}

[7. HD content required to view HD images.](#)

[8. Sold separately or as an optional feature.](#)

[9. Resolutions are dependent upon monitor capability, and resolution and color depth settings.](#)

[10. HP Sure View G3 integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.](#)

[11. Touch-enabled display and Sure View privacy panel will lower actual brightness](#)

Technical Specifications

STORAGE AND DRIVES

Primary M.2 Storage

128 GB SATA TLC Solid State Drive¹²

256 GB PCIe® NVMe™ Value Solid State Drive¹²

512 GB PCIe® NVMe™ Value Solid State Drive¹²

512 GB PCIe® Gen3x4 NVMe™ TLC Solid State Drive¹²

1 TB PCIe® Gen3x4 NVMe™ TLC Solid State Drive¹²

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

MEMORY

Maximum Memory

32GB DDR4-3200 SDRAM (2 x 16 GB)¹³

Memory

32GB DDR4-3200 SDRAM (2 x 16 GB)¹³

16 GB DDR4-3200 SDRAM (1 x 16 GB)

16 GB DDR4-3200 SDRAM (2 x 8 GB)¹³

8 GB DDR4-3200 SDRAM (1 x 8 GB)

8 GB DDR4-3200 SDRAM (2 x 4 GB)¹³

4 GB DDR4-3200 SDRAM (1 x 4 GB)

Memory Slots

2 SODIMM

Both slots are customer accessible / upgradeable by IT or self-maintainers only

DDR4 PC4 SODIMMS, system runs at 3200

Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

Technical Specifications

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wireless-AC 9260 802.11a/b/g/n/ac (2x2) Wi-Fi® and Bluetooth® 5 Combo, non-vPro™¹⁴

Intel® AX200 Wi-Fi 6 (2x2) and Bluetooth® 5 Combo, non-vPro™¹⁵

Realtek RTL8822CE 802.11ac (2x2) WLAN and Bluetooth® 5 Combo¹⁴

Miracast

Native Miracast Support¹⁶

14. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.

15. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited.

Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.

16. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

AUDIO/MULTIMEDIA

Audio

Integrated microphone (Dual Array)

2 Integrated stereo speakers

Speaker Power

2W/4ohm Per speaker

Camera

User-facing 720p HD camera^{7,8}

User-facing 720p HD + IR camera^{7,8}

World-facing 5MP auto-focus secondary camera⁸

Sensors

Combo Chip (Accelerometer + Gyro)

Magnetometer

Hall Sensor

7. HD content required to view HD images.

8. Sold separately or as an optional feature.

Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with DuraKeys and optional backlit¹⁷

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

F1 - Display Switching

F2 - Blank or Privacy (with LED)

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - Insert

F11 - Airplane Mode

F12 - HP Programmable Key

Power Button

Hidden Function Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

17. Backlit keyboard is an optional feature.

Technical Specifications

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen5¹⁸
HP Drive Lock & Automatic Drive Lock¹⁹
BIOS Update via Network
Master Boot Record Security
Power On Authentication
Secure Erase²⁰
Absolute Persistence Module²¹
Pre-boot Authentication

Software

HP Connection Optimizer
HP Image Assistant
HP Hotkey Support
HP JumpStarts
HP Support Assistant²²
HP Noise Cancellation Software
Buy Office (sold separately)
HP Smart Support ⁴⁰

Manageability Features

HP Driver Packs²³
HP System Software Manager (SSM)
HP BIOS Config Utility (BCU)
HP Client Catalog
HP Manageability Integration Kit Gen3²⁴

Client Security Software

HP Client Security Manager Gen6²⁵
Windows Defender²⁶

Security Management

Pre-boot Authentication
TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)
USB enable/disable (via BIOS)
Power-on password (via BIOS)
Setup password (via BIOS)
HP Fingerprint Sensor²⁷
Support for chassis padlocks and cable lock devices
HP Sure Click²⁸
HP Sure Sense²⁹
HP Sure Start Gen5 (for AMD)³⁰

18. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

19. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives

Technical Specifications

20. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
21. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: <https://www.absolute.com/about/legal/agreements/absolute/>
22. HP Support Assistant requires Windows and Internet access.
23. HP Driver Packs not preinstalled, however available for download at <http://www.hp.com/go/clientmanagement>.
24. HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.
25. HP Client Security Manager Gen6 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.
26. Windows Defender Opt in and internet connection required for updates.
27. HP Fingerprint Sensor sold separately or as an optional feature.
28. HP Sure Click is available on select HP platforms and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
29. HP Sure Sense requires Windows 10. See product specifications for availability.
30. HP Sure Start Gen5 for AMD is available on select HP PCs with AMD processors. See product specifications for availability
40. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: <http://www.hp.com/smart-support>. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

Technical Specifications

POWER

Power Supply

HP Smart 65 W External AC power adapter³¹

HP Smart 65 W EM External AC power adapter³¹

HP Smart 65 W USB Type-C™ adapter³¹

HP Smart 45 W External AC power adapter³¹

HP Smart 45 W USB Type-C™ adapter³¹

Primary Battery

HP Long Life 3-cell, 45 Wh Li-ion polymer³²

Support HP Fast Charge (Up to 50% in 30 minutes with 65W AC Adapter)³³

Power Cord

3-wire plug - 1m³¹

2-wire plug - 1m³¹

Battery life

Up to 17 hours and 15 minutes³⁴

31. Availability may vary by country.

32. Battery is internal and not replaceable by customer. Serviceable by warranty.

33. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

34. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See <http://www.bapco.com> for additional details.

WEIGHTS & DIMENSIONS

Weight

Starting at 3.19 lb (1.45 kg)³⁵

Dimensions (w x d x h)

12.15 x 8.78 x 0.71 in

30.85 x 22.29 x 1.79 cm

35. Weight will vary by configuration.

Technical Specifications

PORTS/SLOTS

Ports

- 1 USB 3.1 Type-C™ Gen 1 (Power delivery, DisplayPort™1.4)
- 2 USB 3.1 Gen 1 (1 charging port)
- 1 HDMI 1.4b³⁶
- 1 Headphone/microphone combo jack
- 1 AC power

Expansion Slots

- 1 microSD
- Supports SD, SDHC, SDXC

36. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: <http://www.hp.com/go/cpc>.³⁷

37. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit <http://www.hp.com/go/cpc>. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19 V
	Average Operating Power	5.71 w
	Integrated Graphics	AMD
	Max Operating Power	UMA < 45W
Temperature	Operating	41° to 95° F (5° to 35° C)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
	Non-operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Planned Industry Standard Certifications	UL	Yes
	CSA	Yes
	FCC Compliance	Yes
	ENERGY STAR®	Yes, Select models ³⁸
	EPEAT® 2019	Yes, Gold in U.S. ³⁹
	ICES	Yes
	Australia	Yes
	NZ A-Tick Compliance	Yes
	CCC	Yes
	Japan VCCI Compliance	Yes
	KC	Yes
	BSMI	Yes
	CE Marking Compliance	Yes
	BNCI or BELUS	Yes
	CIT	Yes
	GOST	Yes
	Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes	
UKRSERTCOMPUTER	Yes	

38. Configurations of the HP ProBook x360 435 G7 that are ENERGY STAR® certified are identified as HP ProBook x360 435 G7 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

Technical Specifications

39. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit <http://www.epeat.net> for more information.

DISPLAYS

All specifications represent the typical specifications provided by HP's component manufacturers, actual performance may vary either higher or lower.

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP 1.2 w/o PSR slim	Outline Dimensions (W x H x D)	300.56 x 187.77 mm (max) (w/ PCB & w/o bracket)
	Active Area	293.76 x 165.24 mm (typ.)
	Weight	260 g (max)
	Diagonal Size	13.3 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.2 (2 lane)
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	600:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	250nits (typ.)
	Pixel Resolution	1920 x 1080 (FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% NTSC
	Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85	

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 72% NTSC 400 nits eDP 1.4+PSR2 ultraslim	Outline Dimensions (W x H x D)	299.06 x 185.54 mm (max)
	Active Area	293.76 x 165.24 mm (typ.)
	Weight	170 g (max)
	Diagonal Size	13 inch
	Thickness	2.0 mm (max)
	Interface	eDP 1.4 + PSR2 (2 lane)
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	1200:1 (typ.)

Technical Specifications

Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution	1920 x 1080 (FHD)
Format of LCD Pixel Arrangement	RGB
Backlight	LED
Color Gamut Coverage	72% NTSC
Color Depth	8 bits
Viewing Angle	UWVA 85/85/85/85

Panel LCD 13.3 inch diagonal FHD (1920 x 1080) BrightView WLED UWVA 72% NTSC 1000 nits eDP 1.4+PSR2 flat Privacy NWBZ	Outline Dimensions (W x H x D)	298.76 x 186.04 mm (typ.)
	Active Area	293.76 x 165.24 mm (typ.)
	Weight	255 g (max)
	Diagonal Size	13.3 inch
	Thickness	3.0 mm (max)
	Interface	eDP 1.4 + PSR2
	Surface Treatment	BrightView Glass
	Touch Enabled	Yes
	Contrast Ratio	2000:1 (typ.)
	Refresh Rate	60 Hz
	Brightness	1000 nits*
	Pixel Resolution	1920 x 1080(FHD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	72% NTSC
	Color Depth	8 bit
Viewing Angle	UWVA 85/85/85/85	

[Touch-enabled display and Sure View privacy panel will lower actual brightness](#)

STORAGE

128 GB 2280 M2 SATA-3 TLC Solid State Drive	Form Factor	M.2 2280
	Capacity	128 GB

Technical Specifications

NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Weight	0.02 lb (10 g)
Interface	ATA-8, SATA 3.0
Maximum Sequential Read	Up To 520 MB/s
Maximum Sequential Write	Up To 450 MB/s
Logical Blocks	250,069,680
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	DIPM; TRIM; DEVSLP

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB of disk is reserved for system recovery software.

256 GB 2280 PCIe NVMe Value Solid State Drive

Form Factor	M.2 2280
Capacity	256 GB
NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Weight	0.02 lb (10 g)
Interface	PCIe NVMe
Maximum Sequential Read	Around 1500 ~ 1700 MB/s
Maximum Sequential Write	Around 780 ~ 1300 MB/s
Logical Blocks	500118192
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB of disk is reserved for system recovery software.

SSD 512 GB 2280 M2 PCIe-3x4 SS NVMe TLC

Form Factor	M.2 2280
Capacity	512 GB
NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Weight	0.02 lb (10 g)
Interface	PCIe NVMe Gen3X4
Maximum Sequential Read	Around 2700 ~ 3400 MB/s
Maximum Sequential Write	Around 1390 ~ 2956 MB/s
Logical Blocks	1000215215

Technical Specifications

Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB of disk is reserved for system recovery software.

SSD 512 GB 2280 PCIe NVMe Value

Form Factor	M.2 2280
Capacity	512 GB
NAND Type	TLC/QLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Weight	0.02 lb (10 g)
Interface	PCIe NVMe
Maximum Sequential Read	Around 1500 ~ 1700 MB/s
Maximum Sequential Write	Around 860 ~ 1500 MB/s
Logical Blocks	1000215215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB of disk is reserved for system recovery software.

Technical Specifications

NETWORKING/COMMUNICATIONS

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® and Bluetooth® 5.0	Wireless LAN Standards	<ul style="list-style-type: none"> IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	<ul style="list-style-type: none"> •802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
	Data Rates	<ul style="list-style-type: none"> •802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security²	<ul style="list-style-type: none"> •IEEE 64 / 128-bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware •802.1x authentication •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification •WPA3 certification •IEEE 802.11i •WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum

Technical Specifications

	<ul style="list-style-type: none"> • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP)180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3 v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)

Technical Specifications

LED Activity	LED Amber – Radio OFF LED OFF – Radio ON
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HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX)

Technical Specifications

Basic Imaging Profile (BIP)2
 Headset Profile (HSP)
 Hands Free Profile (HFP)
 Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® Wi-Fi 6⁴ AX200 and Wireless LAN Standards
Bluetooth® 5.0
(802.11ax 2 x 2, non-vPro, supporting gigabit file transfer speeds) non-vPro^{1*}

IEEE 802.11a
 IEEE 802.11b
 IEEE 802.11g
 IEEE 802.11n
 IEEE 802.11ac
 IEEE 802.11ax
 IEEE 802.11d
 IEEE 802.11e
 IEEE 802.11h
 IEEE 802.11i
 IEEE 802.11k
 IEEE 802.11r
 IEEE 802.11v

Interoperability

Wi-Fi certified

Frequency Band

- 802.11b/g/n/ax
2.402 – 2.482 GHz
- 802.11a/n/ac/ax
4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

Data Rates

- 802.11b: 1, 2, 5.5, 11 Mbps
- 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
- 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
- 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
- 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)

Technical Specifications

Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security²	<ul style="list-style-type: none"> •IEEE 64 / 128-bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware •802.1x authentication •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification •WPA3 certification •IEEE 802.11i •WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • 802.11ax HT40(2.4GHz): +10dBm minimum • 802.11ax VHT160(5GHz): +10dBm minimum
Power Consumption	<ul style="list-style-type: none"> •Transmit mode: 2.0 W •Receive mode: 1.6 W •Idle mode (PSP)180 mW (WLAN Associated) •Idle mode: 50 mW (WLAN unassociated) •Connected Standby/Modern Standby: 10mW •Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum

Technical Specifications

Antenna type	802.11ax, MCS11 (VHT160): -58.5dBm maximum High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3 v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
Transmit Power	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software

Technical Specifications

Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited.
2. Check latest software/driver release for updates on supported security features.
3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
4. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
*For full Intel® vPro™ functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See <http://Intel.com/vpro>.

**Intel® 9260
802.11a/b/g/n/ac (2 x 2)
Wi-Fi® and Bluetooth®
5.0 Combo¹ Non-vPro**

Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11d

Technical Specifications

	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	<ul style="list-style-type: none"> •802.11b/g/n 2.402 – 2.482 GHz •802.11a/n/ac 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz
Data Rates	<ul style="list-style-type: none"> •802.11b: 1, 2, 5.5, 11 Mbps •802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) •802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security²	<ul style="list-style-type: none"> •IEEE 64 / 128-bit WEP encryption for a/b/g mode only •AES-CCMP: 128 bit in hardware •802.1x authentication •WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. •WPA2 certification •WPA3 certification •IEEE 802.11i •WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power	<ul style="list-style-type: none"> • 802.11b: +18.5dBm minimum • 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum • 802.11n HT20(2.4GHz): +15.5dBm minimum • 802.11n HT40(2.4GHz): +14.5dBm minimum • 802.11n HT20(5GHz): +15.5dBm minimum • 802.11n HT40(5GHz): +14.5dBm minimum

Technical Specifications

Power Consumption	<ul style="list-style-type: none"> • 802.11ac VHT80(5GHz): +11.5dBm minimum • 802.11ac VHT160(5GHz): +11.5dBm minimum • Transmit mode: 2.0 W • Receive mode: 1.6 W • Idle mode (PSP)180 mW (WLAN Associated) • Idle mode: 50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8 g 2. Type 126: 1.3 g
Operating Voltage	3.3 v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating 0 to 10,000 ft (3,048 m) Non-operating 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF LED OFF – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0 Compliant

Technical Specifications

Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps signaling data rate ¹ 2.17 Mbps BLE: 1 Mbps signaling data rate ¹ 0.2 Mbps 1. Actual throughput may vary.
Transmit Power	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5) The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Technical Specifications

1. Wireless access point and Internet service is required. Availability of public wireless access point is limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices
2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.
4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

POWER

HP 45 W USB type C Straight 1.8 m AC Adapter

Dimensions	94.0 mm x 40.0 mm x 26.5 mm
Weight	192.5 g +/- 10 g (Not including power cord. Power cord varies by country)
Input	<p>Input Efficiency Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%</p> <p>Input frequency range 47 ~ 63 Hz</p> <p>Input AC current Max. 1.4 A at 90 VAC</p>
Output	<p>Output power 5V/15W 9V/27W 12V/36W 15V/45W</p> <p>DC output 5V / 9V / 12V / 15V</p> <p>Hold-up time 5ms at 115 Vac input</p> <p>Output current limit < 5.0A</p>
Connector	USB Type-C™
Environmental Design	<p>Operating temperature 32° to 95° F (0° to 35° C)</p> <p>Non-operating (storage) temperature -4° to 185° F (-20° to 85° C)</p> <p>Altitude 0 to 16,400 ft (0 to 5000m)</p> <p>Humidity 20% to 95%</p> <p>Storage Humidity 10% to 95%</p>
EMI and Safety Certifications	<p>CE Mark - full compliance with LVD and EMC directives</p> <p>Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.</p> <p>MTBF - over 200,000 hours at 25°C ambient condition.</p>

Technical Specifications

HP 45 W Smart AC adapter	Dimensions	3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)	
	Weight	0.386 lb (175g) max (Not including power cord. Power cord varies by country)	
	Input		90 to 265 VAC
		Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.4 A at 90 VAC
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
	Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
Humidity		20% to 95%	
	Storage Humidity	10% to 95%	
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives		
	Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.		
	MTBF - over 200,000 hours at 25°C ambient condition.		

AC Adapter 45 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m 2prong	Dimensions	95.0 x 40.0 x 26.5 mm	
	Weight	200 g +/- 10 g (Not including power cord. Power cord varies by country)	
	Input		87.74% at 115Vac and 88.4% at 230Vac
		Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range	47 ~ 63 Hz
		Input AC current	1.4 A at 90 VAC
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
	Connector	C6	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
Humidity		20% to 95%	
	Storage Humidity	10% to 95%	
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives		

Technical Specifications

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.
MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Standard USB type C Straight 1.8 m	Dimensions	90.0 x 51 x 28.5 mm	
	Weight	250 g +/- 10 g (Not including power cord. Power cord varies by country)	
	Input	Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A	
	Output	Input frequency range	47 ~ 63 Hz
		Input AC current	1.6 A at 90 VAC and maximum load
		Output power	65 W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	5ms at 115 Vac input
	Connector	Output current limit	<8.0A MAXIMUM
			USB Type-C™
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
Humidity		20% to 95%	
EMI and Safety Certifications	Storage Humidity	10% to 95%	
		CE Mark - full compliance with LVD and EMC directives	
		Worldwide safety standards -IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 65 Watt Smart nPFC EM Barrel 4.5 mm New EM	Dimensions	102 x 55 x 30 mm
	Weight	250 g +/- 10 g (Not including power cord. Power cord varies by country)
	Input	Input Efficiency 88.0 % at 115 Vac and 89.0 % at 230Vac

Technical Specifications

Output	Input frequency range	47 ~ 63 Hz
	Input AC current	1.7 A at 90 Vac
	Output power	65 W
	DC output	19.5 V
	Hold-up time	5ms at 115 Vac input
	Output current limit	<11.0 A
Connector	C6	
Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

AC Adapter 65 Watt Smart nPFC Standard Barrel 4.5 mm Right Angle 1.8 m

Dimensions	90.0 x 51 x 28.5 mm	
Weight	230 g +/- 10 g (Not including power cord. Power cord varies by country)	
Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
	Input frequency range	47 ~ 63 Hz
Output	Input AC current	1.7 A at 90 Vac
	Output power	65 W
	DC output	19.5 V
	Hold-up time	5ms at 115 Vac input
	Output current limit	<11.0 A
Connector	4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords	
Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
	Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.	

Technical Specifications

Battery SX 3 Cell WHr 45 Long Life -PL Fast Charge	Dimensions (H x W x L)	184.62 x 85.25 x 6.15 mm	
	Weight	0.195 kg Max	
	Cells/Type	3cell Lithium-Ion Polymer cell	
	Energy	Voltage	13.2V / 11.55V (13.2V / 11.4V)
		Amp-hour capacity	3.9 Ah / 3.75 Ah (3.95 Ah / 3.79 Ah)
	Temperature	Watt-hour capacity	45 Wh
		Operating (Charging)	32° to 113° F (0° to 45° C)
		Operating (Discharging)	14° to 122° F (-10° to 60° C)
	Optional Travel Battery Available	No	
	Warranty	Based on system offering	

COUNTRY OF ORIGIN

China

Options and Accessories (sold separately and availability may vary by country)

Type	Description	Part #
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP TB Dock G2 w/ Combo Cable	3TR87AA
	HP TB Dock 120W G2 w/Audio	3YE87AA
	HP TB Dock 120W G2 cable	3XB94AA
	HP TB Dock G2 combo cable	3XB96AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP TB Dock G2 Audio Module	3AQ21AA
	HP USB-C/A Universal Dock G2	5TW13AA
	HP USB-C Dock G5	5TW10AA
Input/Output	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP USB Fingerprint Mouse	4TS44AA
	HP USB-C to DP	N9K78AA
	HP USB-C to USB-A Hub	Z6A00AA
	HP Elite USB-C Multi Port Hub	4WX89AA
	HP Pro Pen	8JU62AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	HP 65W Smart AC Adapter 4.5mm	H6Y89AA
	HP 45W LC USB-C Power Adapter	1MZ01AA
	HP 65W LC USB-C Power Adapter	TBD
	USB-C NB Power Bank	1TZ86AA
	HP Essential Power Bank	3TB55AA
Storage	HP External USB Optical Drive	F2B56AA
Memory	HP 4GB DDR4 3200 Memory	286H5AA
	HP 8GB DDR4 3200 Memory	286H8AA
	HP 16GB DDR4 3200 Memory	286J1AA

Options and Accessories (sold separately and availability may vary by country)

Security

HP Sure Key Cable Lock

6UW42AA

HP Nano Keyed Cable Lock

1AJ39AA">

Summary Changes

Date of change:	Version History:		Description of change:
	From V1 to V2		Processors, 1 TB storage, and updated military standards information.
	From V2 to V3		Memory updated
January 21, 2021	From V3 to V4	Added	WPA3 certification in Security, Networking section
April 19, 2021	From V4 to V5	Updated	Memory Section Updated
May 6, 2021	From V5 to V6	Added	HP Smart Support
June 15, 2021	From V6 to V7	Removed	HP USB-C to RJ45 Adapter from Options and Accessories section

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